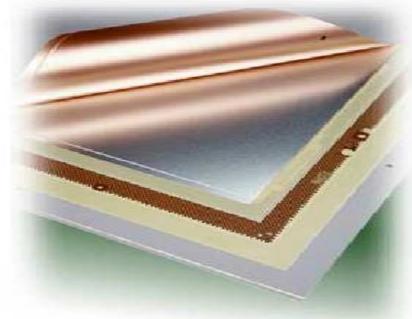


ABC

ALUMINIUM BETWEEN COPPER



A simple solution for multilayer

ABC is a combination of Copper/Aluminium/Copper which have been bonded together using an ultrasonic process developed and patented by MITSUI Mining Smelting (MMS-Japan).

This product is available in various sizes with wide range of Copper combined with high-grade Aluminium separator foils

BENEFITS

- | | |
|-------------------------------|--|
| •Higher first pass yields | Outerlayer circuit surfaces protected from air Particulate during the lay up process, thus ensuring That they are free from resin spots and dust |
| •Handling problems eliminated | no wrinkles in copper, related defects also greatly reduced
No issues with registration and handling of thin Copper foils (9 μ ,12 μ m, 18 μ m...) |
| •Increase press capacity | The number of boards per daylight can be increased significantly (>30%) |

ABC

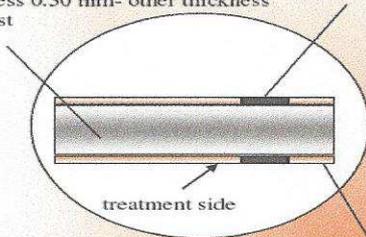
ALUMINIUM BETWEEN COPPER

SPECIFICATIONS

CONSTRUCTION

ALUMINIUM

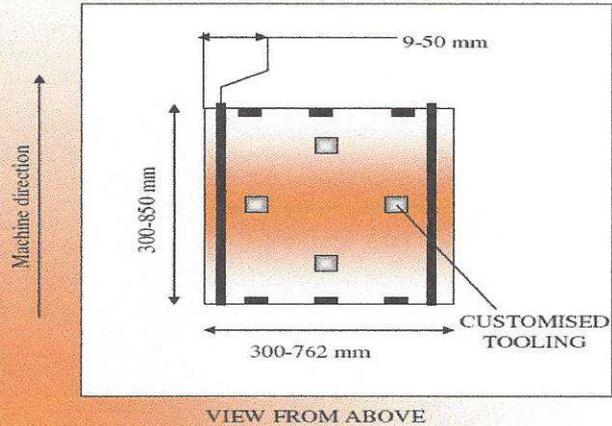
- Highly controlled surface hardness **ULTRASONIC**
- Mg alloy grade (Rm > 320 N / mm²) **WELDING**
- Thickness 0.30 mm- other thickness on request



COPPER FOILS

- ABC is exclusively built with Copper Foil Manufactured by MITSUI in accordance with IPC 4562 Class 3
- Thickness range from 9µ to 35µm

PANEL CAPABILITY



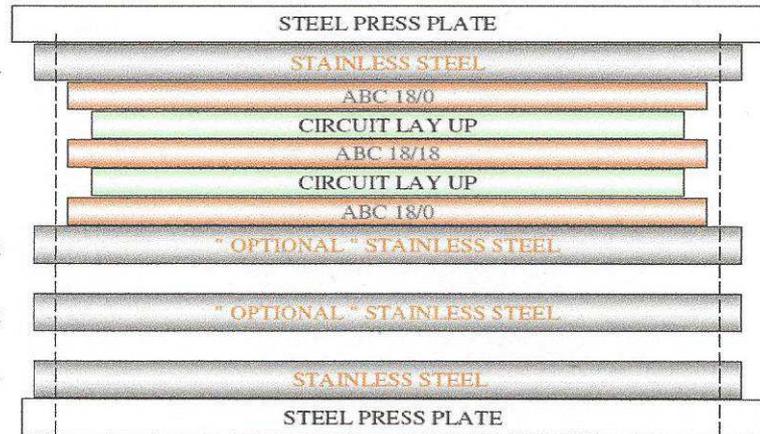
PROCESSING

Example : 15 panels/opening instead of 11 when using steel (circuit thickness = 1.5 mm)

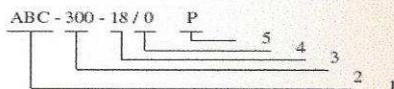
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ORDERING INFORMATION



1. Product reference
2. Aluminium thickness
3. Copper foil top
4. Copper foil bottom
5. Punched